



PK614 (v1.0) September 10,
2013

100% Material Declaration Data Sheet for 7 Series FFG1930 Package

Average Weight: 25.9100 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.893576	3.449%
	Silicon	7440-21-3	100.00	Basis	0.893576	
Solder Bump					0.043347	0.167%
	Tin	7440-31-5	63.00	Basis	0.027309	
	Lead	7439-92-1	37.00	Basis	0.016038	
Underfill					0.093450	0.361%
	Bisphenol F	9003-36-5	20.00	Basis	0.018690	
	Phenolic Resin	Trade Secret	15.00	Basis	0.014018	
	Epoxy Resin	25068-38-6	5.00	Basis	0.004673	
	Amine type Accelerator	Trade Secret	5.00	Basis	0.004673	
	Silicon Dioxide	60676-86-0	51.50	Filler	0.048127	
	Carbon Black	1333-86-4	1.00	Color Agent	0.000935	
Additives	Trade Secret	2.50	Additives	0.002336		
Solder Paste					0.014400	0.056%
	Tin	7440-31-5	96.50	Metal	0.013896	
	Silver	7440-22-4	3.00	Metal	0.000432	
	Copper	7440-50-8	0.50	Metal	0.000072	
Capacitor 1					0.041280	0.159%
	BaTiO3 type	12047-27-7	70.60	Ceramic	0.029144	
	Nickel	7440-02-0	6.70	Inner Electrode	0.002766	
	Copper	7440-50-8	20.10	Outer Electrode	0.008297	
	Nickel	7440-02-0	0.80	Plating 1	0.000330	
	Tin	7440-31-5	1.80	Plating 2	0.000743	
Capacitor 2					0.022800	0.088%
	BaTiO3 type	12047-27-7	61.70	Ceramic	0.014068	
	Nickel	7440-02-0	4.89	Inner Electrode	0.001115	
	Indium tin oxide	50926-11-9	18.30	Outer Electrode	0.004172	
	Copper	7440-50-8	13.40	Outer Electrode	0.003055	
	Nickel	7440-02-0	0.49	Plating 1	0.000112	
Tin	7440-31-5	1.22	Plating 2	0.000278		

© Copyright 2013 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners

100% Material Declaration Data Sheet – 7 Series FFG1930

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Capacitor 3					0.003600	0.014%
	BaTiO3 type	12047-27-7	66.00	Ceramic	0.002376	
	Nickel	7440-02-0	2.67	Inner Electrode	0.000096	
	Copper	7440-50-8	23.33	Outer Electrode	0.000840	
	Nickel	7440-02-0	2.33	Plating 1	0.000084	
	Tin	7440-31-5	5.67	Plating 2	0.000204	
Capacitor 4					0.016740	0.065%
	BaTiO3	12047-27-7	51.10	Ceramic	0.008554	
	Nickel	7440-02-0	27.00	Inner Electrode	0.004520	
	Copper	7440-50-8	16.00	Outer Electrode	0.002678	
	Glass	65997-17-3	0.90		0.000151	
	Nickel	7440-02-0	2.00	Plating 1	0.000335	
	Tin	7440-31-5	3.00	Plating 2	0.000502	
Heat Sink					14.214000	54.859%
	Copper	7440-50-8	99.15	Main Material	14.093181	
	Nickel	8049-31-8	0.85	Main Material	0.120819	
Heat Sink Adhesive					0.357000	1.378%
	Aluminium Oxide	1344-28-1	70.00	Main Material	0.249900	
	Dimethyl Siloxane	68083-19-2	30.00	Main Material	0.107100	
Solder Ball					1.607244	6.203%
	Tin	7440-31-5	96.50	Main Material	1.550990	
	Silver	7440-22-4	3.00	Main Material	0.048217	
	Copper	7440-50-8	0.50	Main Material	0.008036	
Substrate					8.602573	33.202%
	Copper	7440-50-8	48.53		4.174780	
	Tin	7440-31-5	0.08		0.00694	
	Lead	7439-92-1	0.11		0.009659	
	Silver	7440-22-4	0.47		0.040774	
	BT Core	N/A	39.52		3.399440	
	ABF	N/A	10.28		0.884560	
	Solder Mask	N/A	1.00		0.086420	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/10/13	1.0	Initial Xilinx release.

Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers (“Contractors”). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.